WINSTON & STRAWN DOCKET NO.: 4717-6300

_ (if applicable)

DECLARATION FOR NON-PROVISIONAL PATENT APPLICATION

As a below named inventor, I hereby declare that:

is attached hereto and includes amendment(s) filed on

and for which a patent application:

My residence, post office address and citizenship are as stated below at 201 et seq. beneath my name.

I believe I am the original, first and sole inventor if only one name is listed at 201 below, or an original, first and joint inventor if plural names are listed at 201 et seq. below, of the subject matter which is claimed and for which a patent is sought on the invention entitled

METHOD AND APPARATUS FOR ADJUSTING THE THICKNESS OF A LAYER OF SEMICONDUCTOR MATERIAL

was filed in the United States	on as Application N	lo		(declaration not
accompanying application) w was filed as PCT internationa	I Application No.	on		and was amended
under PCT Article 19 on			(if applic	cable)
I hereby state that I have revie amended by any amendment refe		ents of the above identifi	ied application, inc	cluding the claims, as
I acknowledge the duty to disclo Regulations, § 1.56.	se information known to me to	be material to patentabili	ity as defined in Tit	le 37, Code of Federa
I hereby claim foreign priority be inventor's certificate listed below a filing date before that of the ap	and have also identified below	w any foreign application	of any foreign appl for patent or inven	ication(s) for patent of tor's certificate having
EARLIEST FOREIGN APP	PLICATION(S), IF ANY, FILE	ED PRIOR TO THE FILI	NG DATE OF THE	E APPLICATION
APPLICATION NUMBER	COUNTRY	DATE OF FILIN (day, month, yea	יוועע ו	PRITY CLAIMED
0210208	France	August 12, 200	02 × YES	S □ NO
0210209	France	August 12, 200	02 🛛 YES	S 🔲 NO
I hereby claim the benefit unde below. PROVISIONAL APPI		e, § 119(e) of any Unite	FILING DATE	al application(s) listed

I hereby claim the benefit under as the subject matter of each of t provided by the first paragraph of me which is material to patentab the filing date of the prior applica	the claims of this application is of Title 35, United States Code ility as defined in Title 37, Coe	s not disclosed in the prio e § 112, I acknowledge the de of Federal Regulations	r United States app ne duty to disclose s, § 1.56 which beca	olication in the manner information known to
NON-PROVISIONAL	FILING DATE	STATUS		
APPLICATION NO.	TILING DATE	PATENTED	PENDING	ABANDONED
				

- 1 -

^{*} for use only when the application is assigned to a company, partnership or other organization.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

FULL NAME OF		LAST NAME	FIRST NAME	MIDDLE NAME	
2	INVENTOR	GHYSELEN	Bruno		
	RESIDENCE &	CITY	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP	
0	CITIZENSHIP	Seyssinet-Pariset	France	France	
1	POST OFFICE	STREET	CITY	STATE OR COUNTRY	ZIP CODE
	ADDRESS	58 rue Georges Maeder	Seyssinet-Pariset	France	38170
					<u> </u>
		SIGNATURE OF LAURENT VIRAVAUX		DATE	
	FULL NAME OF	LAST NAME	FIRST NAME	MIDDLE NAME	
2	INVENTOR	AULNETTE	Cécile		
0	RESIDENCE &	CITY	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP	
	CITIZENSHIP	Grenoble	France	France	
2	POST OFFICE	STREET	CITY	STATE OR COUNTRY	ZIP CODE
	ADDRESS	3 Place des Tilleuls	Grenoble	France	38000
		SIGNATURE OF INVENTOR 202		DATE	
			T		
	FULL NAME OF	LAST NAME	FIRST NAME	MIDDLE NAME	
2	INVENTOR	OSTERNAUD	Bénédite		
0	RESIDENCE &	CITY	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP	
	CITIZENSHIP	Saint Egreve	France	France	
3	POST OFFICE			STATE OR COUNTRY	ZIP CODE
	ADDRESS	26 rue Lieutenant Fiancey	Saint Egreve	France	38120
		SIGNATURE OF INVENTOR 203		DATE	

NY:797862.1